

ABSTRACT OF THE INVENTION

In a semiconductor integrated circuit device including a plurality of semiconductor devices formed on a substrate, the principal plane of the substrate is partitioned into a 5 plurality of device regions and into a plurality of routing regions each crossing a boundary between the plural device regions. A device group including one or more semiconductor devices among the plural semiconductor devices and a local interconnect for connecting the semiconductor devices 10 included in the device group are disposed within the plural device regions. A global routing for connecting the device groups to each other is disposed within each of the plural routing regions.